

PRODUCT SPECIFICATION

Part Number
PLH2427SA4-WCRGB1

Details

- 2.4 x 2.7 x 1.1mm RGB LED with integrated IC.

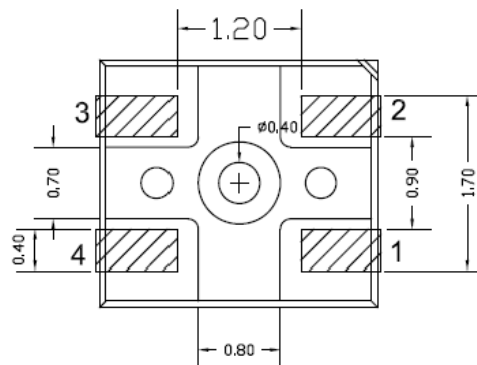
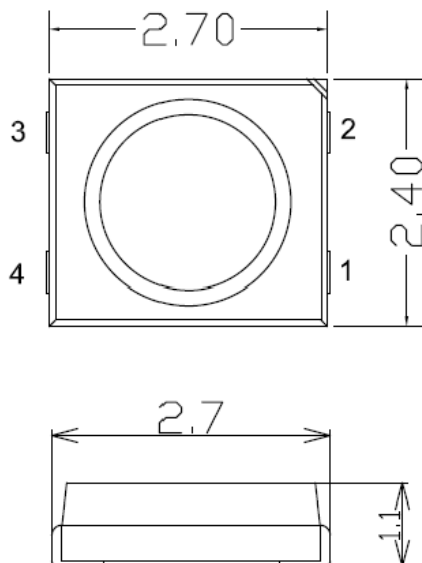
Applications

- Full color LED string light
- LED full color module
- LED guardrail tube
- LED scene lighting
- LED point light
- LED pixel screen
- LED shaped screen

Features

- 2427 with integrated high quality constant current IC and RGB LED chip..
- Built-in IC, with high precision of constant current and internal RGB chips spectral processing in advance.
- Single line data transmission (return to zero code).
- Specific Shaping Transmit Technology - number of LED stacked is not restricted.
- Cascading Enhancement Technology - any 2 LED spacing can be up to 10 meter
- Data transfer rate of 750 kbp/s at 30 frames per • LED full color module second.
- RGB output port PWM control can achieve 256 grey level adjustments.
- Upon powering up, IC performs self-inspection then lights connection on the pin B lamp
- SA-I anti-interference patent technology for single line data transmission
- Built-in power supply reverse connect protection module, reversed power input will not damage the IC.

Package Outline Dimensions & Pin Configuration

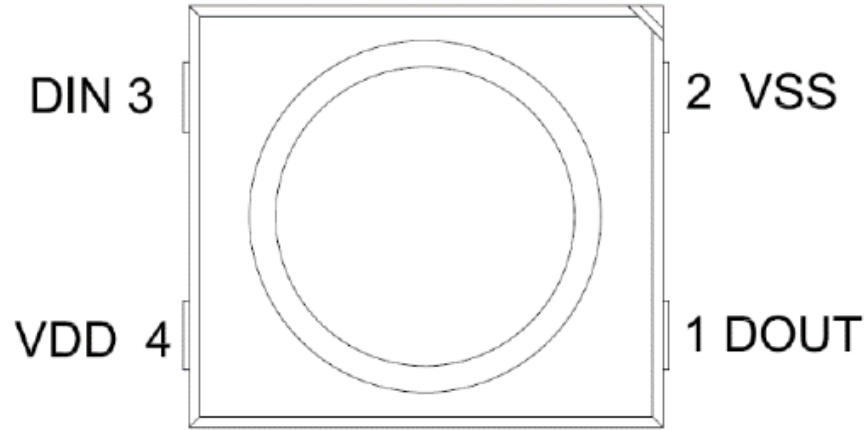


Note:

1. Specifications subject to change without notice

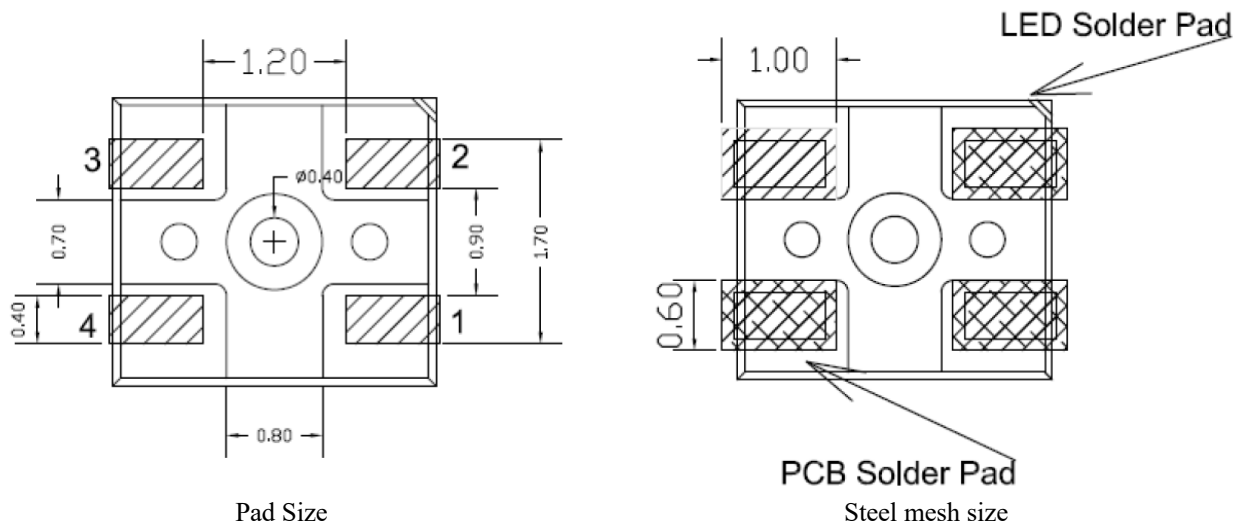


Pin Configuration



Number	Symbol	Function Description
1	DOUT	Control data signal output
2	VSS	Ground
3	DIN	Control data signal input
4	VDD	Power supply LED

Soldering Pad Size



Notes:

1. Dimension in millimeter, tolerance is $\pm 0.1\text{mm}$ unless otherwise noted.

Absolute Maximum Rating ($T_a = 25\text{ }^{\circ}\text{C}$, $V_{SS}=0V$)

Parameter	Symbol	Range	Unit
Power supply voltage	V_{DD}	+3.5 ~ +5.5	V
Logic input voltage	V_{IN}	-0.5 ~ $V_{DD}+0.5$	V
Working temperature	T_{OPT}	-45 ~ +85	$^{\circ}\text{C}$
Storage temperature	T_{STG}	-50 ~ +150	$^{\circ}\text{C}$
ESD pressure(HBM)	V_{ESD}	4K	V
ESD pressure(DM)	V_{ESD}	200	V

LED Characteristics ($T_a = 25^{\circ}\text{C}$)

Color	5mA	
	Wavelength(nm)	Light Intensity(mcd)
Red	620-630	100-200
Green	520-535	400-700
Blue	460-475	50-100

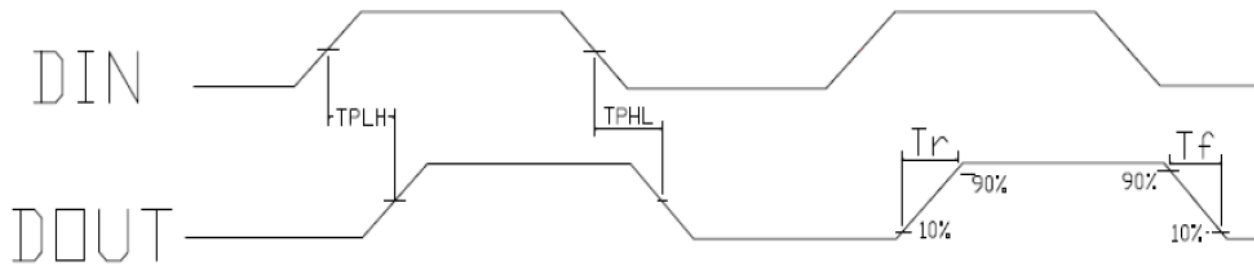
Recommended Operating Ranges

(unless otherwise specified, $T_a = -20 \sim +70\text{ }^{\circ}\text{C}$, $V_{DD} = 4.5 \sim 5.5\text{V}$, $V_{SS} = 0\text{V}$)

Parameter	Symbol	Min.	Typ.	Max	Unit	Test conditions
Supply voltage	V_{DD}	-	5.2	-	V	-
R/G/B port pressure	$V_{DS, MAX}$	-	-	26	V	-
DOUT drive capability	I_{DOH}	-	49	-	mA	DOUT connect ground, the maximum drive current
DOUT drive capability	I_{DOL}	-	-50	-	mA	DOUT connect +, the largest current
The signal input flip threshold	V_{IH}	3.4	-		V	$V_{DD} = 5.0\text{V}$
The signal input flip threshold	V_{IL}	-	-	1.6	V	$V_{DD} = 5.0\text{V}$
The frequency of PWM	F_{PWM}	-	1.2	-	KHZ	-
Static power consumption	I_{DD}	-	1	-	mA	-

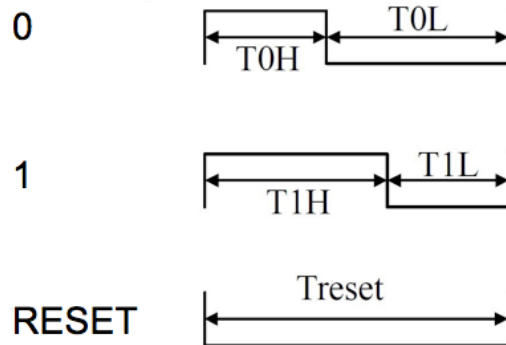
Switching Characteristics (unless otherwise specified, $T_A=25\text{ }^{\circ}\text{C}$)

Parameter	Symbol	Min.	Typ.	Max	Unit	Test conditions
The speed of data transmission	f_{DIN}	-	800	-	KHZ	The duty ratio of 67% (data 1)
DOUT transmission delay	T_{PLH}	-	-	500	ns	DIN→DOUT
	T_{PHL}	-	-	500	ns	
I_{OUT} Rise/Drop Time	T_r	-	100	-	ns	VDS=1.5 VIOU=13mA
	T_f	-	100	-	ns	



Timing Waveforms

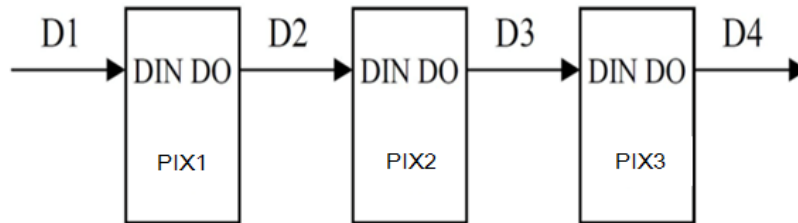
1. Input Code



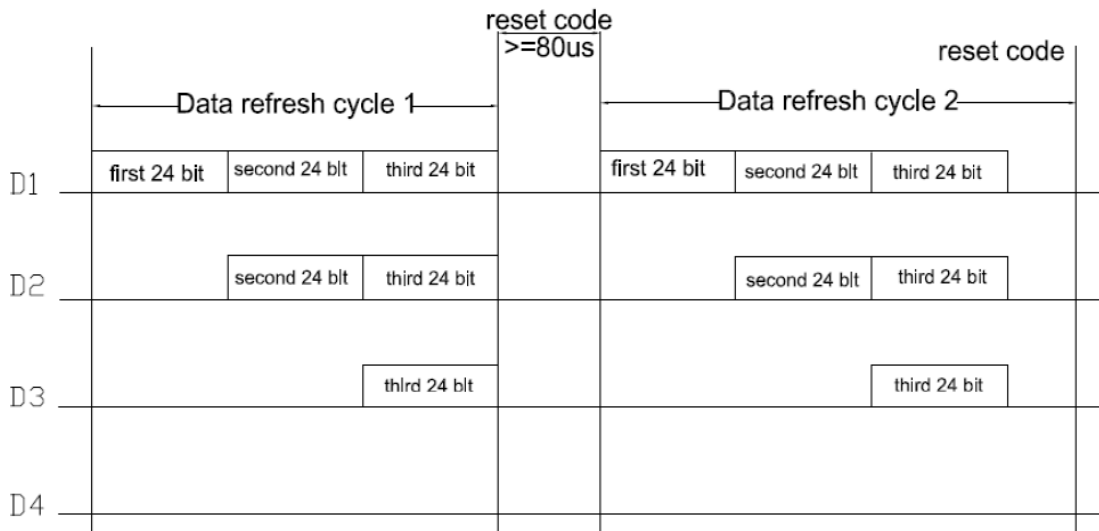
2. The data transmission time ($T_H + T_L = 1.25\mu s \pm 600ns$):

Name	Description	Typ. value	error
T0H	0 code, high level time	0.3 μs	$\pm 0.15\mu s$
T0L	0 code, low level time	0.9 μs	$\pm 0.15\mu s$
T1H	1 code, high level time	0.9 μs	$\pm 0.15\mu s$
T1L	1 code, low level time	0.3 μs	$\pm 0.15\mu s$
Trst	Reset code, low level time	80 μs	

3. Connection Scheme



4. Method of data transmission



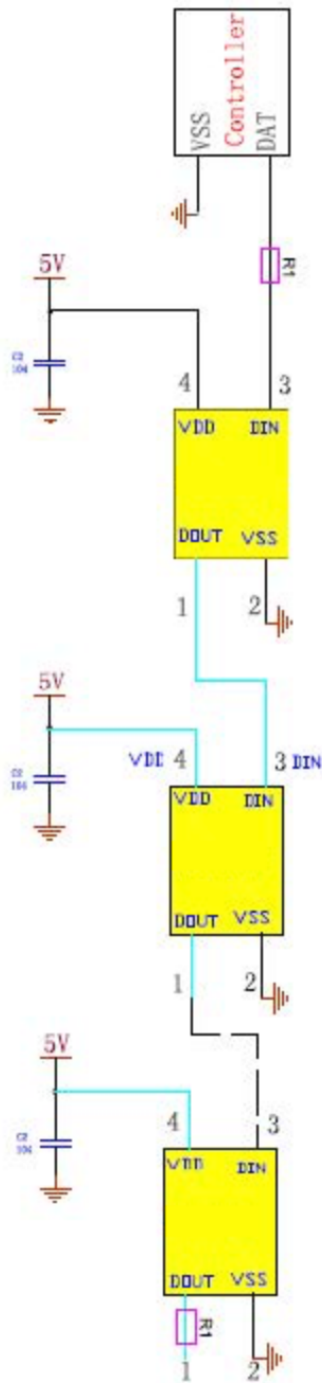
Note: the D1 sends data for MCU, D2, D3, D4 for data forwarding automatic shaping cascade circuit.

5. 24-bit data format

G7	G6	G5	G4	G3	G2	G1	G0	R7	R6	R5	R4
R3	R2	R1	R0	B7	B6	B5	B4	B3	B2	B1	B0

Note: high starting, in order to send data (G7 - G6 - -B0)

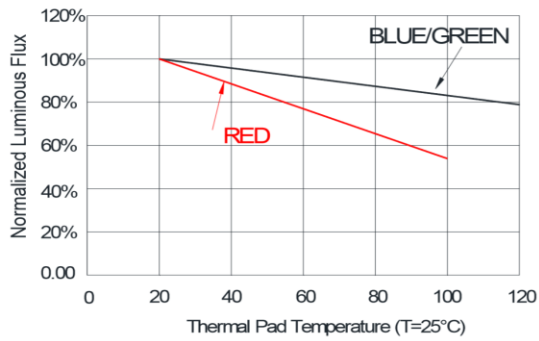
Typical Application Circuit



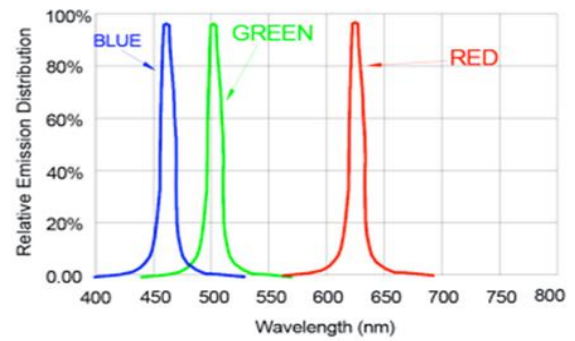
Product signal input and output must be connected in series with protection resistor R1. R1 depends on the size of the cascade amount, the greater the number of cascades, the smaller R1. The general recommended value is between 200-2KΩ, usually the recommended value is typical 500Ω.

LED Performance Graph

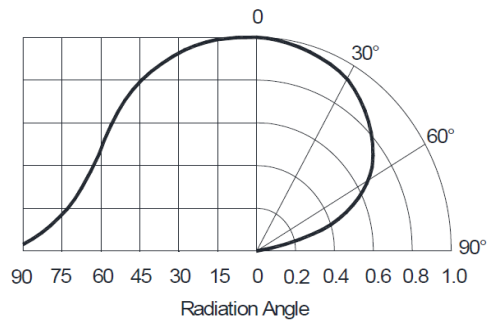
Thermal Pad Temperature vs. Relative Light Output



Wavelength Characteristics



Typical Radiation Pattern 120°





Precautions

Please read the following notes before using the product:

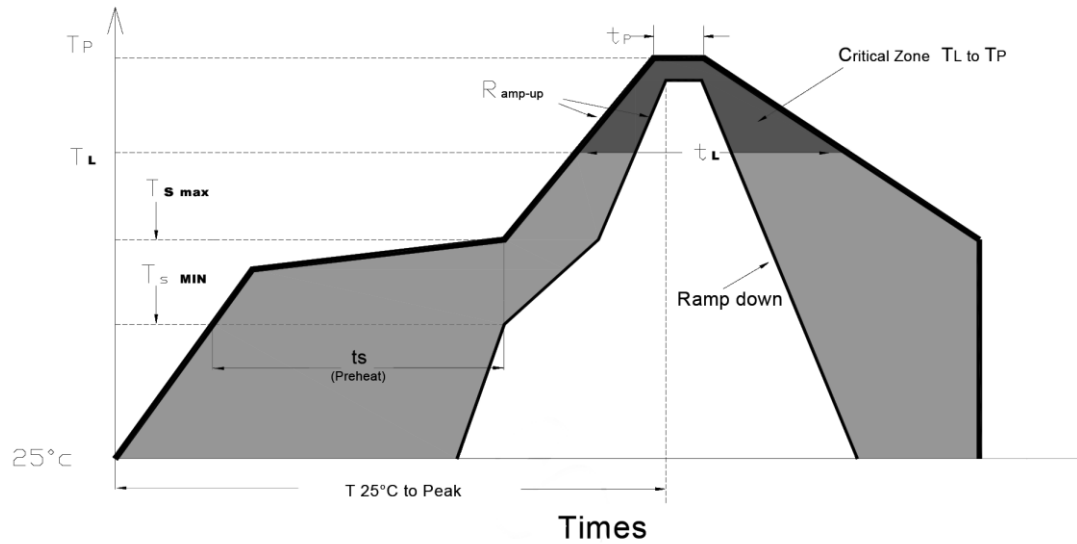
1. Storage

- 1.1 Do not open moisture proof bag before the products are ready to use.
- 1.2 Before opening the package, the LEDs should be kept at 30°C or less and 80%RH or less.
- 1.3 The LEDs should be used within a year.
- 1.4 After opening the package, the remaining LEDs should be kept in a resealed bag.
- 1.5 The LEDs require mandatory baking before usage. Baking treatment listed below.
- 1.6 If the moisture adsorbent material has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

*Baking treatment: 60±5°C for 24 hours.

2. Soldering Condition

Recommended soldering conditions:



Profile Feature	Lead-Free Solder
Average Ramp-Up Rate ($T_S \text{ max}$ to T_P)	3°C/second max.
Preheat: Temperature Min ($T_S \text{ min}$)	150°C
Preheat: Temperature Min ($T_S \text{ max}$)	200°C
Preheat: Time ($t_s \text{ min}$ to $t_s \text{ max}$)	60-180 seconds
Time Maintained Above: Temperature (T_L)	217 °C
Time Maintained Above: Time (t_L)	60-150 seconds
Peak/Classification Temperature (T_P)	240 °C
Time Within 5°C of Actual Peak Temperature (t_P)	<10 seconds
Ramp-Down Rate	6°C/second max.
Time 25 °C to Peak Temperature	<6 minutes max.

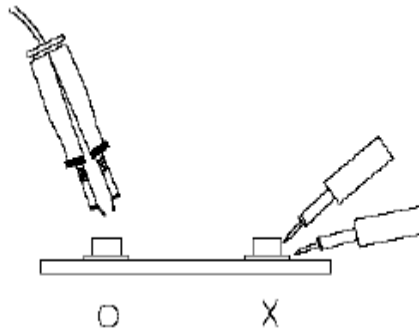
Note: Excessive soldering temperature and / or time might result in deformation of the LED lens or catastrophic failure of the LED.

3. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 260°C for 5 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

4. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



5. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wristband or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded. Re: da

[illegible]